Amendments to the Claims:

1. (Previously Amended) A method for preparing a thin supported film on a metal substrate having two opposing surfaces, the method comprising:

a. masking off a first surface of the metal substrate with a maskant, leaving a second surface of the metal substrate unmasked;

b. placing the metal substrate under a vacuum;

c. treating the unmasked second surface of the metal substrate by plasma etching;

d. coating the treated second surface of the metal substrate by plasma etching;

d. coating the treated second surface of the metal substrate with a film while still under vacuum;

e. removing the metal substrate from the vacuum;

f. removing the maskant from the first surface after the treated second surface is coated with the film;

g. forming a photoresist on the first surface from which the maskant is removed, the photoresist exposing a part of the first surface of the photoresist;

h. etching through the part of the substrate of which the first surface is exposed by the photoresist; and

i. removing the photoresist.

2. (Currently Amended) The method of Claim 1, wherein the metal substrate is a stainless steel substrate.

3. (Currently Amended) The method of Claim 1, wherein the metal substrate is a brass substrate.

4. (Currently Amended) The method of Claim 1, wherein the metal substrate is a silicon substrate.

5. (Currently Amended) The method of Claim 1, wherein the maskant is a tape.

6. (Previously Amended) The method of Claim 1, wherein the maskant is made from liquid film.

7. (Original) The method of Claim 1, wherein the maskant is resist.

8. (Original) The method of Claim 1, wherein the maskant is wax.

9. (Original) The method of Claim 1, wherein the thin supported film is produced by plasma arc deposition.

10. (Original) The method of Claim 1, wherein the thin supported film is produced by vapor deposition.

11. (Original) The method of Claim 1, wherein the thin supported film is parylene.

12. (Previously Amended) A thin supported film on a metal substrate having two opposing surfaces created by a method comprising:

a. masking off a first surface of the two opposing surfaces with a maskant, leaving a second surface of the two opposing surfaces;

b. placing the metal substrate under a vacuum;

c. treating the unmasked second surface of the metal substrate by plasma etching;

d. coating the treated second surface of the metal substrate with a film;

e. removing the metal substrate from the vacuum;

f. removing the maskant from the first surface after coating second surface with the maskant;

g. forming a photoresist layer on the first surface to expose a desired pattern of the first surface;

h. removing the desired pattern of the first surface; and

i. removing the photoresist layer from the first surface.

13. (Origial) The thin supported film on the metal substrate of Claim 12, wherein the metal substrate is stainless steel.

14. (Previously Amended) The thin supported film on the metal substrate of Claim 12, wherein the metal substrate is brass.

15. (Original) The thin supported film on the metal substrate of Claim 12, wherein the metal substrate is silicon.

16. (Original) The thin supported film on the metal substrate of Claim 12, wherein the maskant is tape.

17. (Currently Amended) The thin supported film on the metal substrate of Claim 12, wherein the ~~metal substrate~~ maskant is made from liquid film.

18. (Original) The thin supported film on the metal substrate of Claim 12, wherein the maskant is resist.

19. (Original) The thin supported film on the metal substrate of Claim 12, wherein the maskant is wax.

20. (Original) The thin supported film on the metal substrate of Claim 12, wherein the thin supported film is produced by vapor deposition.

21. (Original) The thin supported film on the metal substrate of Claim 12, wherein the thin supported film is produced by plasma arc deposition.

22. (Original) The thin supported film on the metal substrate of Claim 12, wherein the thin supported film is parylene.